Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.034 x .034”**

**.039”**

**.039”**

**Top Material: Al**

**Backside Material: Ag**

**Bond Pad Size: .034” X .034”**

**Backside Potential: Cathode**

**Mask Ref: SENS665**

**APPROVED BY: DK DIE SIZE .039” X .039” DATE: 9/2/21**

**MFG: SENSITRON THICKNESS .010” P/N: 1N5819**

**DG 10.1.2**

#### Rev B, 7/19/02